

2MBI75VA-170-50

IGBT Modules

IGBT MODULE (V series) 1700V / 75A / 2 in one package

Features

High speed switching Voltage drive Low Inductance module structure

Applications

Inverter for Motor Drive AC and DC Servo Drive Amplifier Uninterruptible Power Supply Industrial machines, such as Welding machines

■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at T_c=25°C unless otherwise specified)



Items	Symbols	Conditions	Conditions		Units	
Collector-Emitter voltage	Vces				V	
Gate-Emitter voltage	V _{GES}				V	
Collector current	Ic	Continuous	Tc=100°C	75		
		Continuous	Tc=25°C	110		
	I _{C pulse}	1ms		150	Α	
	- I c			75		
	-Ic pulse	1ms	1ms			
Collector power dissipation	Pc	1 device		555	W	
Junction temperature	Tj			175		
Operating junction temperature (under switching conditions)	T _{jop}			150	°C	
Case temperature	Tc			125		
Storage temperature	T _{stg}					
Isolation voltage between terminal and copper base (*1)	Viso	AC: 1min.		4000	VAC	
Screw torque Mounting (*2)	-			5.0	N m	
Terminals (*3)	-			5.0	IN III	

Note *1: All terminals should be connected together when isolation test will be done. Note *2: Recommendable Value : $3.0\sim5.0~N\cdot m~(M5~or~M6)$ Note *3: Recommendable Value : $2.5\sim5.0~N\cdot m~(M5)$

● Electrical characteristics (at T_i= 25°C unless otherwise specified)

ltama	Symbolo	Conditions		Characteristics			Heite
Items	Symbols			min.	typ.	max.	Units
Zero gate voltage collector current	Ices	V _{GE} = 0V, V _{CE} = 1700V		-	-	1.0	mA
Gate-Emitter leakage current	Iges	$V_{CE} = 0V, V_{GE} = \pm 20V$		-	-	200	nA
Gate-Emitter threshold voltage	V _{GE (th)}	V _{CE} = 20V, I _C = 75mA		6.0	6.5	7.0	V
Collector-Emitter saturation voltage	V	V _{GE} = 15V Ic = 75A	T _j =25°C	-	2.10	2.55	V
	V _{CE (sat)}		T _j =125°C	-	2.55	-	
	(terminal)		T _j =150°C	-	2.60	-	
	V		T _j =25°C	-	2.00	2.45	
	V _{CE} (sat)		T _j =125°C	-	2.40	-	
	(chip)		T _j =150°C	-	2.45	-	
Internal gate resistance	R _G (int)	-		-	10	-	Ω
Input capacitance	Cies	V _{CE} = 10V, V _{GE} = 0V, f = 1MHz		-	8.2	-	nF
Turn-on time	ton	V _{cc} = 900V, I _c = 75A V _{GE} = ±15V, Rg_on=Rg_off= 22Ω T _j =150°C, L _s = 30nH		-	1250	-	nsec
	tr			-	550	-	
	t _{r (i)}			-	70	-	
Turn-off time	toff			-	1300	-	
	t f			-	150	-	
Forward on voltage	.,	V _{GE} = 0V I _F = 75A	T _j =25°C	-	1.85	2.30	V
	V _F		T _j =125°C	-	2.10	-	
	(terminal)		T _j =150°C	-	2.10	-	
	.,		T _i =25°C	-	1.80	2.25	
	V _F		T _j =125°C	-	2.05	-	
	(chip)		T _j =150°C	-	2.05	-	
Reverse recovery time	trr	I _F = 75A		-	140	-	nsec

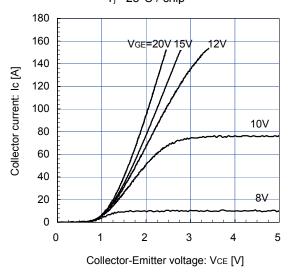
Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units	
Items		Conditions	min.	typ.	max.	Units	
Thermal resistance(1device)	R _{th(j-c)}	IGBT	-	-	0.27	°C/W	
		FWD	-	-	0.50		
Contact thermal resistance (1device) (*4)	R _{th(c-f)}	with Thermal Compound	-	0.050	-		

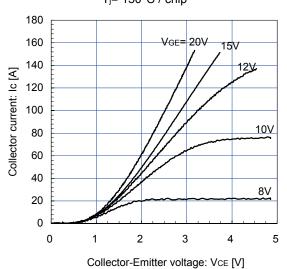
Note *4: This is the value which is defined mounting on the additional cooling fin with thermal compound.

■ Characteristics (Representative)

Collector current vs. Collector-Emitter voltage (typ.) T_j= 25°C / chip

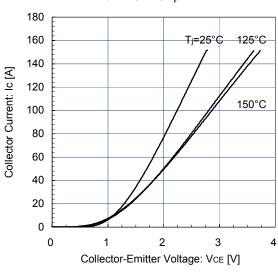


Collector current vs. Collector-Emitter voltage (typ.) T_j= 150°C / chip

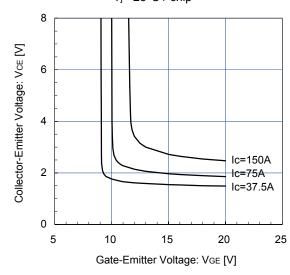


Collector current vs. Collector-Emitter voltage (typ.)

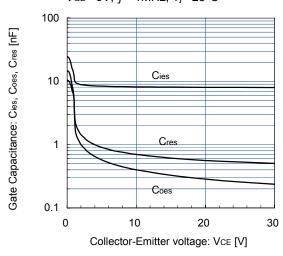
VGE= 15V / chip



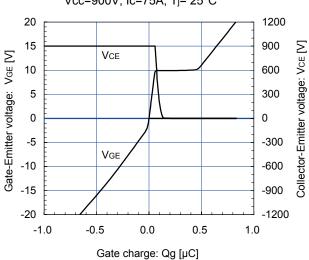
Collector-Emitter voltage vs. Gate-Emitter voltage T_i= 25°C / chip



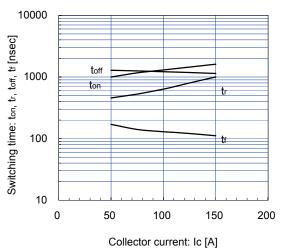
Gate Capacitance vs. Collector-Emitter Voltage V_{GE} = 0V, f = 1MHz, T_{j} = 25°C



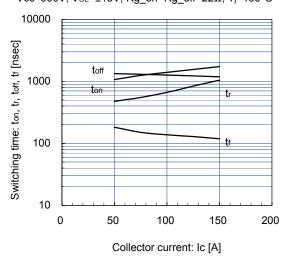
Dynamic Gate Charge (typ.) Vcc=900V, Ic=75A, T_j= 25°C



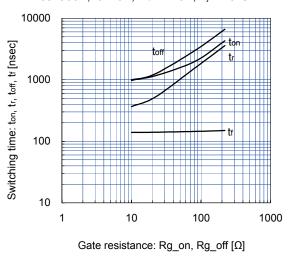
Switching time vs. Collector current (typ.) Vcc=900V, V $_{GE}$ =±15V, Rg_on=Rg_off=22 Ω , T $_{j}$ =125 $^{\circ}$ C



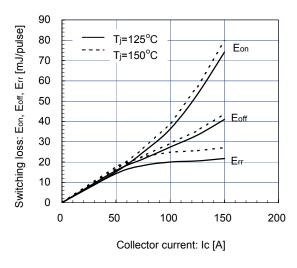
Switching time vs. Collector current (typ.) Vcc=900V, VgE= \pm 15V, Rg_on=Rg_off= 22Ω , Tj=150°C



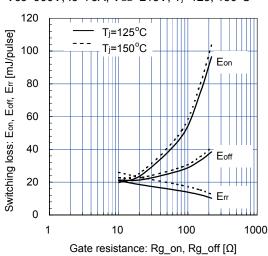
Switching time vs. Gate resistance (typ.) Vcc=900V, Ic=75A, VgE=±15V, Tj=125°C



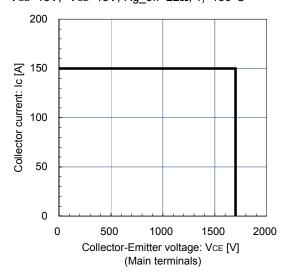
Switching loss vs. Collector current (typ.) Vcc=900V, V_{GE}=±15V, Rg_on=Rg_off=22Ω



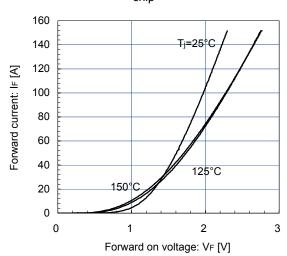
Switching loss vs. Gate resistance (typ.) Vcc=900V, Ic=75A, V_{GE}=±15V, T_j=125, 150°C



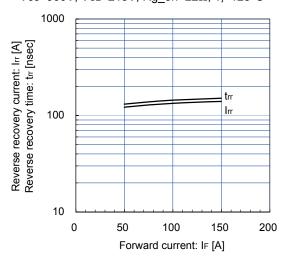
Reverse bias safe operating area (max.) + V_{GE} =15V, - V_{GE} =15V, Rg_off=22 Ω , Tj=150°C



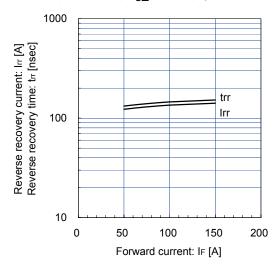
Forward Current vs. Forward Voltage (typ.) chip



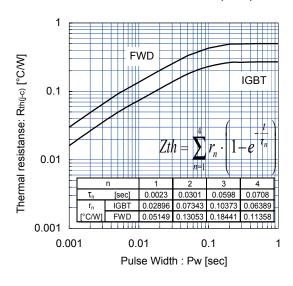
Reverse Recovery Characteristics (typ.) Vcc=900V, $V_{GE}=\pm15V$, $Rg_on=22\Omega$, $T_j=125^{\circ}C$



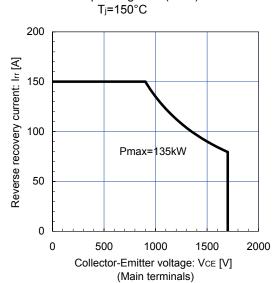
Reverse Recovery Characteristics (typ.) Vcc=900V, $VgE=\pm15V$, $Rg_on=22\Omega$, $T_j=150^{\circ}C$



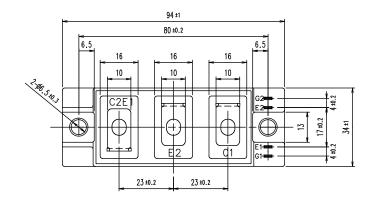
Transient Thermal Resistance (max.)

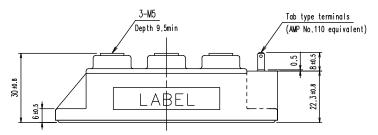


FWD safe operating area (max.)



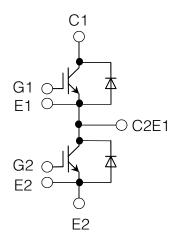
■ Outline Drawings, mm





Weight: 180g (typ.)

■ Equivalent Circuit Schematic



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- Measurement equipment

- Machine tools
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- Electrical home appliances Personal equ
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• Traffic-signal control equipment

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- Safety devices
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